

Welcome to O-leading

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service - S/S in 24hrs , 4-8layers in 48-96 working hrs production time.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

Product Description

[led pcb board Printed circuit board](#)
[Printed circuit board in china](#)
[pcb manufacturer in china](#)

Quick Details

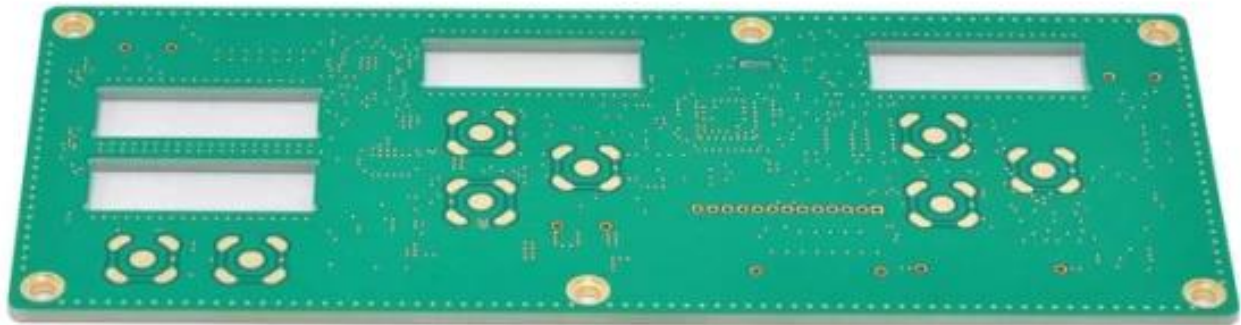
| | | | |
|-------------------|--|-------------------|------------------------|
| Place of Origin | Guang dong, China (Mainland) | Brand Name | O-Leading |
| Base Material | FR-4,,Aluminum | Copper Thickness | 0.5oz-5oz |
| Min. Hole Size | 0.2mm | Min. Line Width | 0.2mm |
| Surface Finishing | immersion gold ,OSP,lead free HASL | Board Thickness | 0.1-5mm |
| applicable to | led,mobile phone,air conditioners,washing machines | character | Industrial Control pcb |
| certificates | ISO9001,UL,RoHS,SGS | Q/CTN | 10PCS-100PCS |
| weight | 0.01kg -5kg | MOQ | 10pcs |
| color | blue ,red ,green,black,yellow | Min. Line Spacing | 0.2mm |
| Model Number | power bank pcb assembly pcha manufacturer | price | \$0.1-\$10 |
| design type | client requirement | size | 0.01m3-10m3 |

Packaging & Delivery

| | |
|--------------------|--|
| Packaging Details: | 16 years professional OEM pcb board manufacturer |
| Delivery Detail: | 7-12days |

Product Description

| item | 2014 | | 2015~2016 | | 2017~2018 | |
|---|--|--------|-----------|--------|-----------|--------|
| | Volume | Sample | Volume | Sample | Volume | Sample |
| Layer count | 32 | 42 | 38 | 44 | 42 | 48 |
| Min Line/space (µm) | 50/50 | 40/45 | 40/45 | 40/40 | 35/40 | 35/35 |
| Min drill hole diameter (mm) | 0.15 | 0.10 | 0.15 | 0.10 | 0.15 | 0.10 |
| Aspect ratio of PTH | 14:1 | 16:1 | 16:1 | 18:1 | 18:1 | 20:1 |
| N+C+N | 4+C+4 | 5+C+5 | 5+C+5 | 6+C+6 | 5+C+5 | 6+C+6 |
| Any layer interconnection | 5+2+5 | 6+2+6 | 5+2+5 | 6+2+6 | 5+2+5 | 6+2+6 |
| Plate filling via | YES | -- | YES | -- | YES | -- |
| Min. core thickness (exclude copper) (µm) | 50 | 40 | 40 | 30 | 40 | 30 |
| Min. Laser Drill diameter (µm) | 75 | 65 | 65 | 50 | 50 | 40 |
| Via on buried hole/stacked via | YES | -- | YES | -- | YES | -- |
| Material | FR4, Megtron, Nelco, Rogers, Heavy Copper, etc. | | | | | |
| Embedded capacitor PCB | YES | -- | YES | -- | YES | -- |
| Surface Process | Lead-free HASL, ENIG, OSP, Immersion silver, Immersion tin, Flash gold, Gold finger plating, Selective hard gold plating, Peelable solder mask, Carbon ink | | | | | |



www.o-leading.com

Our Team





Certifications



QUALITY MANAGEMENT SYSTEM CERTIFICATE
 Certificate No.: 16118Q10347R05

We hereby certify that
O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED
 Credit No.: 61691591-000-07-17-2
 Registration Add: ROOM 603D 6/F HANG PONT COMMERCIAL BUILDING,31 TONKIN ST,CHEUNG SHA WAN,KL, HK
 Business Add: 1313 Floor 13 Fortune Building, Danshui Town Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System**
 Which fulfills the requirements of the following standards
 GB/T19001-2016 idt ISO9001:2015

Scope of certification
 Sales of printed circuit boards

Initial Issuance period: February 27, 2018
 This certificate is valid during: February 27, 2018 -- February 26, 2021
 This certificate is invalid without CICC qualified label in the following period

| | | | |
|-----------------------------|----------------|------------------------------|----------------|
| First supervision and audit | Qualified mark | Second supervision and audit | Qualified mark |
|-----------------------------|----------------|------------------------------|----------------|

The certification registration scope does not include those products/services scopes which fail to be covered by the relevant effective administrative permission and qualification permission required by the state. The effectiveness of this certificate shall be evaluated by annual surveillance audit of CICC. The certificate shall be valid when used together with the surveillance audit conclusion. The related information of this certification can be searched at the public website of company www.cicc.com.cn.

201726 201VZL430354 - Wiring, Printed - Component

ONLINE CERTIFICATIONS DIRECTORY

ZPMV2.E490354
Wiring, Printed - Component

For enhanced search functionality, please visit [UL's Family of Databases](#).
 Click on a product designation for complete information.
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Wiring, Printed - Component

See General Information for Wiring, Printed - Components

O-LEADING SUPPLY CHAIN CO LIMITED E490354
 Fortune Building, Nanheng West Road
 Room 1313
 Huizhou, Guangdong 516211, CHINA

| | Cond Width | | | SS/ DS/ Diam | Area | Solder | | Dper | | Flame | RoHS | C |
|--|---------------|---------------|---------------------|--------------|------------|--------|-----|------|-------|-------|------|---|
| | Min | Max | Edge | | | Min | Max | Temp | Class | | | |
| Typ | max(in) | mm(in) | mic(mil) | DS0 | mm(in) | C | sec | C | Class | DSR | I | |
| Hull/Bayer (mass laminate) printed wiring boards. | | | | | | | | | | | | |
| O-LEADING-401 | | | | | | | | | | | | |
| | 0.2 (0.004) | 0.3 (0.012) | 34 (1.34) | D6 | 12.7 (0.5) | 260 | 10 | 130 | V-0 | - | - | |
| O-LEADING-407 | | | | | | | | | | | | |
| | 0.08 (0.003) | 0.2 (0.008) | 17 (0.67) | D5 | 9.2 (0.4) | 260 | 10 | 130 | V-0 | NI | - | |
| Hull/Bayer printed wiring boards. | | | | | | | | | | | | |
| O-LEADING-408 | | | | | | | | | | | | |
| | 0.125 (0.005) | 0.125 (0.005) | 12 (0.47) 31-135 | D6 | 50.8 (2.0) | 260 | 20 | 130 | V-0 | NI | * | |
| Single layer printed wiring boards. | | | | | | | | | | | | |
| O-LEADING-002 | | | | | | | | | | | | |
| | 0.76 (0.015) | 1.14 (0.045) | 34 (1.34) | SS | 19.1 (0.8) | 260 | 10 | 105 | V-0 | NI | - | |
| O-LEADING-003 | | | | | | | | | | | | |
| | 0.38 (0.015) | 1.14 (0.045) | 34 (1.34) | SS | 19.1 (0.8) | 260 | 10 | 130 | V-0 | ▲ | - | |
| O-LEADING-033 | | | | | | | | | | | | |
| | 0.15 (0.006) | 0.3 (0.012) | 34 (1.34) | SS | 25.4 (1.0) | 260 | 10 | 120 | V-0 | NI | - | |
| O-LEADING-205 | | | | | | | | | | | | |
| | 0.1 (0.004) | 0.3 (0.012) | 34 (1.34) | D6 | 69.6 (2.7) | 260 | 10 | 130 | V-0 | NI | - | |
| O-LEADING-206 | | | | | | | | | | | | |
| | 0.15 (0.006) | 0.33 (0.013) | 17 (0.67) | D5 | 69.6 (2.7) | 260 | 10 | 130 | V-0 | NI | - | |

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.
 Last updated on 2017-01-27

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Test Report No. CAVEC1805164701 Date: 03 Apr 2018 Page 2 of 8

Test Results:
 Test Part Description:
 Specimen No. **SGS Sample ID Description**
 SN1 CA18-051647.001 Green "PCB"

Remarks:
 (1) 1 mg/kg = 1 ppm = 0.0001%
 (2) MDL = Method Detection Limit
 (3) ND = Not Detected (< MDL)
 (4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method: With reference to IEC 62321-4:2014+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

| Test Item(s) | Limit | Unit | MDL | Det |
|----------------------------|-------|-------|-----|-----|
| Cadmium (Cd) | 100 | mg/kg | 2 | ND |
| Lead (Pb) | 1,000 | mg/kg | 2 | 9 |
| Mercury (Hg) | 1,000 | mg/kg | 2 | ND |
| Hexavalent Chromium (CrVI) | 1,000 | mg/kg | 8 | ND |
| Sum of PBBs | 1,000 | mg/kg | - | ND |
| Monobromobiphenyl | - | mg/kg | 5 | ND |
| Dibromobiphenyl | - | mg/kg | 5 | ND |
| Tribromobiphenyl | - | mg/kg | 5 | ND |
| Tetrabromobiphenyl | - | mg/kg | 5 | ND |
| Pentabromobiphenyl | - | mg/kg | 5 | ND |
| Hexabromobiphenyl | - | mg/kg | 5 | ND |
| Heptabromobiphenyl | - | mg/kg | 5 | ND |
| Octabromobiphenyl | - | mg/kg | 5 | ND |
| Nonabromobiphenyl | - | mg/kg | 5 | ND |
| Decabromobiphenyl | - | mg/kg | 5 | ND |
| Sum of PBDEs | 1,000 | mg/kg | - | ND |
| Monobromodiphenyl ether | - | mg/kg | 5 | ND |
| Dibromodiphenyl ether | - | mg/kg | 5 | ND |
| Tribromodiphenyl ether | - | mg/kg | 5 | ND |
| Tetrabromodiphenyl ether | - | mg/kg | 5 | ND |
| Pentabromodiphenyl ether | - | mg/kg | 5 | ND |

Member of the SGS Group (SGL SA)

Packaging & Delivery

| | |
|-------------------|--|
| Packaging Details | 16 years professional OEM pcb board manufacturer |
| Delivery Detail | 7-12days |



FAQ

1. How do O-Leading ensure quality?

Our high quality standard is achieved with the following.

- 1.The process is strictly controlled under ISO 9001:2008 standards.
- 2.Extensive use of software in managing the production process
- 3.State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
- 4.Dedicated quality assurance team with failure case analysis process
- 5.Continuous staff training and education

2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly. However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edge on cost and quality.

3. What kinds of boards can O-Leading process?

Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

4. What data are needed for PCB production?

It is best to provide data in Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What's the typical process flow for multi-layer PCB?

Material cutting → Inner dry film → inner etching → Inner AOI → Multi-bond → Layer stack up
Pressing → Drilling → PTH → Panel Plating → Outer Dry Film → Pattern Plating → Outer etching →
Outer AOI → Solder Mask → Component Mark → Surface finish → Routing → E/T → Visual Inspection.